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REMARKS

In view of the following remarks, Applicant respectfully requests reconsideration and allowance of the subject application.

Claims 1, 11 and 13 have been rejected under 35 U.S.C. 102(b) as
5 allegedly being anticipated by Lee et al. Claims 1, 3-11, 16-18 have been
rejected under 35 USC 103(a) as allegedly being unpatentable over Then in view
of Bower. Claim 2 has been rejected under 35 USC 103(a) as allegedly being
unpatentable over Then in view of Bower as applied above, and further in view
of Shimada. Claims 12, 14 and 15 have been rejected under 35 USC 103(a) as
10 allegedly being unpatentable over Lee as applied above, and further in view of
Shimada. Claims 24-26 have been rejected under 35 USC 103(a) as allegedly
being unpatentable over Then in view of Bower as applied above, and further in
view of Lai. These rejections are respectfully traversed.

Claims 1 and 11 recite: "...patterning and etching the masking
15 layer to form a hole therethrough, wherein the hole exposes the substrate;
depositing a first layer over the masking layer and in the hole on the exposed
substrate...wherein the plug substantially plugs up the slot." Claim 1 further
recites "etching a back side of the substrate until a bottom surface of the plug is
substantially exposed and a slot in the substrate is substantially formed, wherein
20 the plug substantially plugs up the slot, and wherein the plug substantially
defines a fluid-feed passageway extending between the slot and a firing
chamber."

Claim 24 recites: "...patterning and etching the first masking layer to
form a hole therethrough, wherein the hole exposes the substrate; depositing a
25 front side protection layer over the first masking layer and in the hole on the
exposed substrate... wherein the plug substantially plugs up the slot"

Claim 31 recites: "depositing a first layer over the masking layer and in
the hole and physically contacting the substrate below the hole to create an
interface between the substrate and the first layer" and "etching from a back side

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of the substrate to an interface of the substrate and the first layer at the plug, thereby substantially forming a slot in the substrate with the plug substantially plugging up the slot."

Because neither Lee et al, as applied above, Then et al, as applied above,
5 Bower as applied above, Shimada as applied above, nor Lai as applied above teaches, suggests or discloses the claimed language of claims 1, 11, 24, or 31, these cited references cannot anticipate nor render obvious claims 1, 11, 24 and 31. Therefore, claims 1, 11, 24 and 31 are patentable.

Because claims 2-10, 12-18, 25-26 depend from either claims 1, 11, or 24,
10 and contain additional limitations that are patentably distinguishable over the cited references, these claims are also considered to be patentable.

Claims 32-41 are added and recite novel features not shown or taught in the recited art.

In view of the foregoing remarks, consideration and allowance of this
15 application is respectfully requested. If the Examiner believes that a telephone conference with applicant's attorney, Paul Mitchell, might expedite prosecution of this application, the Examiner is invited to call (509) 324-9256.

CONCLUSION

20 Claims 1-18, 24-25 and 31-41 are in believed to be in condition for allowance. Applicant respectfully requests reconsideration and prompt issuance of the present application. Should any issue remain that prevents immediate issuance of the application, the Examiner is encouraged to contact the undersigned attorney to discuss the unresolved issue.

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Respectfully Submitted,
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Dated:

8/20/03



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